

**OptiMOS<sup>®</sup> -T Power-Transistor**

**Features**

- N-channel - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (RoHS compliant)
- Ultra low Rds(on)
- 100% Avalanche tested

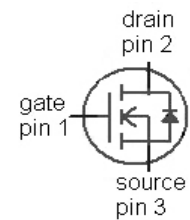
**Product Summary**

|                            |     |    |
|----------------------------|-----|----|
| $V_{DS}$                   | 40  | V  |
| $R_{DS(on)}$ (SMD Version) | 2.5 | mΩ |
| $I_D$                      | 100 | A  |

PG-TO263-3-2    PG-TO262-3-1    PG-TO220-3-1



| Type           | Package      | Marking |
|----------------|--------------|---------|
| IPB100N04S3-03 | PG-TO263-3-2 | 3PN0403 |
| IP1100N04S3-03 | PG-TO262-3-1 | 3PN0403 |
| IPP100N04S3-03 | PG-TO220-3-1 | 3PN0403 |


**Maximum ratings, at  $T_j=25\text{ °C}$ , unless otherwise specified**

| Parameter                           | Symbol         | Conditions                            | Value        | Unit |
|-------------------------------------|----------------|---------------------------------------|--------------|------|
| Continuous drain current            | $I_D$          | $T_C=25\text{ °C}, V_{GS}=10V^{(1)}$  | 100          | A    |
|                                     |                | $T_C=100\text{ °C}, V_{GS}=10V^{(2)}$ | 100          |      |
| Pulsed drain current <sup>(2)</sup> | $I_{D,pulse}$  | $T_C=25\text{ °C}$                    | 400          |      |
| Avalanche energy, single pulse      | $E_{AS}$       | $I_D=80\text{ A}$                     | 898          | mJ   |
| Gate source voltage                 | $V_{GS}$       |                                       | ±20          | V    |
| Power dissipation                   | $P_{tot}$      | $T_C=25\text{ °C}$                    | 214          | W    |
| Operating and storage temperature   | $T_j, T_{stg}$ |                                       | -55 ... +175 | °C   |
| IEC climatic category; DIN IEC 68-1 |                |                                       | 55/175/56    |      |

| Parameter                                      | Symbol     | Conditions                                   | Values |      |      | Unit |
|--|------------|--|--------|------|------|------|
|  |            |  | min.   | typ. | max. |      |
| <b>Thermal characteristics<sup>2)</sup></b>    |            |  |        |      |      |      |
| Thermal resistance, junction - case            | $R_{thJC}$ |  | -      | -    | 0.7  | K/W  |
| Thermal resistance, junction - ambient, leaded | $R_{thJA}$ |  | -      | -    | 62   |      |
| SMD version, device on PCB                     | $R_{thJA}$ | minimal footprint                            | -      | -    | 62   |      |
|  |            | 6 cm <sup>2</sup> cooling area <sup>3)</sup> | -      | -    | 40   |      |

**Electrical characteristics, at  $T_j=25\text{ }^\circ\text{C}$ , unless otherwise specified**
**Static characteristics**

|                                  |               |   |     |     |     |               |
|----------------------------------|---------------|---|-----|-----|-----|---------------|
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | $V_{GS}=0\text{ V}, I_D=1\text{ mA}$  | 40  | -   | -   | V             |
| Gate threshold voltage           | $V_{GS(th)}$  | $V_{DS}=V_{GS}, I_D=150\text{ }\mu\text{A}$                                 | 2.1 | 3.0 | 4.0 |               |
| Zero gate voltage drain current  | $I_{DSS}$     | $V_{DS}=40\text{ V}, V_{GS}=0\text{ V}, T_j=25\text{ }^\circ\text{C}$       | -   | -   | 1   | $\mu\text{A}$ |
|                                  |               | $V_{DS}=40\text{ V}, V_{GS}=0\text{ V}, T_j=125\text{ }^\circ\text{C}^{2)}$ | -   | -   | 100 |               |
| Gate-source leakage current      | $I_{GSS}$     | $V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$                                     | -   | -   | 100 | nA            |
| Drain-source on-state resistance | $R_{DS(on)}$  | $V_{GS}=10\text{ V}, I_D=80\text{ A}$                                       | -   | 2.2 | 2.8 | m $\Omega$    |
|                                  |               | $V_{GS}=10\text{ V}, I_D=80\text{ A},$<br>SMD version                       | -   | 1.9 | 2.5 |               |

| Parameter | Symbol | Conditions | Values |      |      | Unit |
|-----------|--------|------------|--------|------|------|------|
|           |        |            | min.   | typ. | max. |      |

**Dynamic characteristics<sup>2)</sup>**

|                              |              |   |   |      |      |    |
|------------------------------|--------------|---|---|------|------|----|
| Input capacitance            | $C_{iss}$    | $V_{GS}=0\text{ V}, V_{DS}=25\text{ V},$<br>$f=1\text{ MHz}$                    | - | 7400 | 9600 | pF |
| Output capacitance           | $C_{oss}$    |   | - | 2000 | 2600 |    |
| Reverse transfer capacitance | $C_{rss}$    |   | - | 310  | 465  |    |
| Turn-on delay time           | $t_{d(on)}$  | $V_{DD}=20\text{ V}, V_{GS}=10\text{ V},$<br>$I_D=80\text{ A}, R_G=3.3\ \Omega$ | - | 30   | -    | ns |
| Rise time                    | $t_r$        |   | - | 16   | -    |    |
| Turn-off delay time          | $t_{d(off)}$ |   | - | 46   | -    |    |
| Fall time                    | $t_f$        |   | - | 17   | -    |    |

**Gate Charge Characteristics<sup>2)</sup>**

|                       |               |  |   |     |     |    |
|-----------------------|---------------|--|---|-----|-----|----|
| Gate to source charge | $Q_{gs}$      | $V_{DD}=32\text{ V}, I_D=80\text{ A},$<br>$V_{GS}=0\text{ to }10\text{ V}$ | - | 38  | 50  | nC |
| Gate to drain charge  | $Q_{gd}$      |  | - | 25  | 45  |    |
| Gate charge total     | $Q_g$         |  | - | 110 | 145 |    |
| Gate plateau voltage  | $V_{plateau}$ |  | - | 5.2 | -   | V  |

**Reverse Diode**

|  |               |   |   |      |     |    |
|--|---------------|---|---|------|-----|----|
| Diode continuous forward current <sup>2)</sup> | $I_S$         | $T_C=25\text{ }^\circ\text{C}$  | - | -    | 100 | A  |
| Diode pulse current <sup>2)</sup>              | $I_{S,pulse}$ |   | - | -    | 400 |    |
| Diode forward voltage                          | $V_{SD}$      | $V_{GS}=0\text{ V}, I_F=80\text{ A},$<br>$T_J=25\text{ }^\circ\text{C}$   | - | 0.85 | 1.3 | V  |
| Reverse recovery time <sup>2)</sup>            | $t_{rr}$      | $V_R=20\text{ V}, I_F=50\text{ A},$<br>$di_F/dt=100\text{ A}/\mu\text{s}$ | - | 60   | -   | ns |
| Reverse recovery charge <sup>2)</sup>          | $Q_{rr}$      |   | - | 95   | -   | nC |

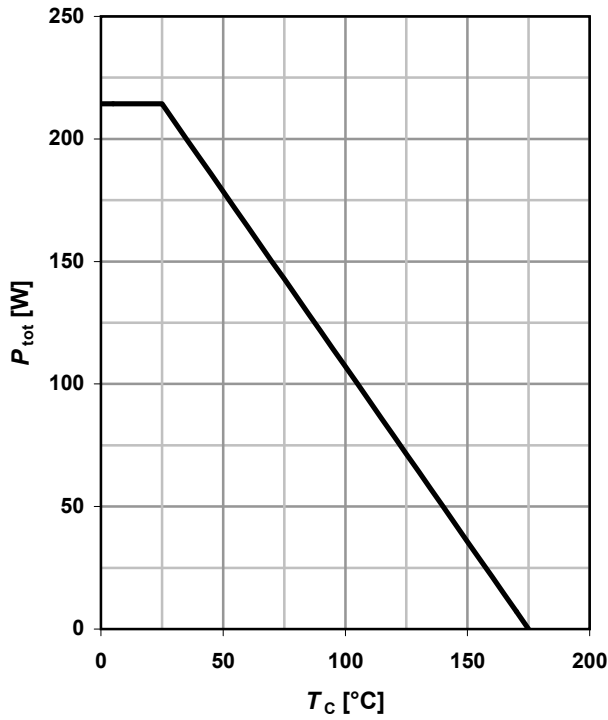
<sup>1)</sup> Current is limited by bondwire; with an  $R_{thJC} = 0.7\text{ K/W}$  the chip is able to carry 218 A at 25°C. For detailed information see Application Note ANPS071E at [www.infineon.com/optimos](http://www.infineon.com/optimos)

<sup>2)</sup> Defined by design. Not subject to production test.

<sup>3)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

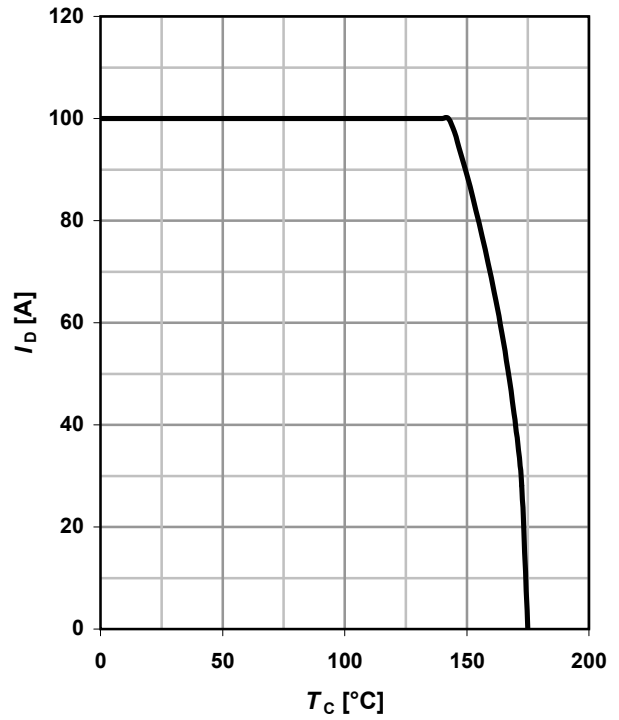
**1 Power dissipation**

$P_{tot} = f(T_C); V_{GS} \geq 6\text{ V}$



**2 Drain current**

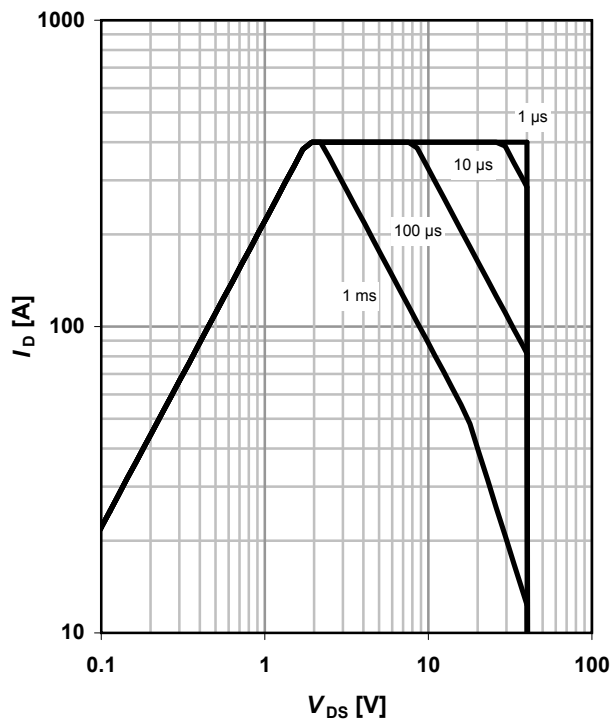
$I_D = f(T_C); V_{GS} \geq 6\text{ V}$



**3 Safe operating area**

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0$

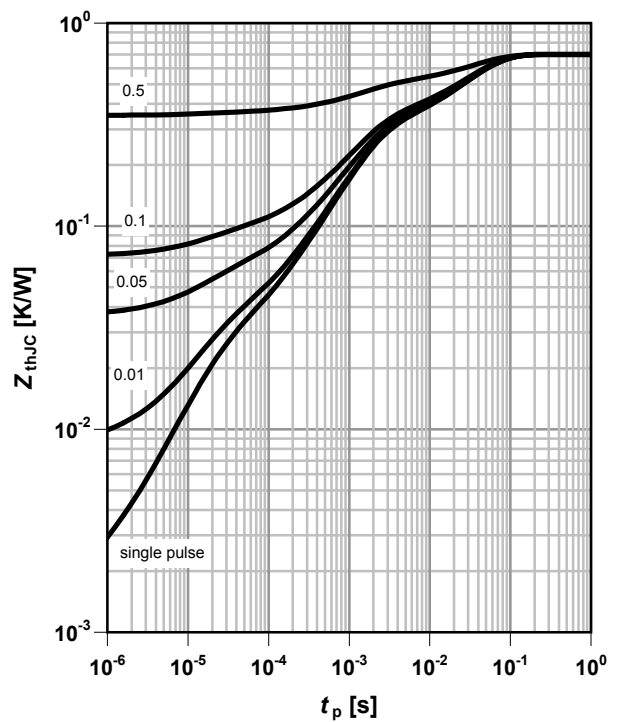
parameter:  $t_p$



**4 Max. transient thermal impedance**

$Z_{thJC} = f(t_p)$

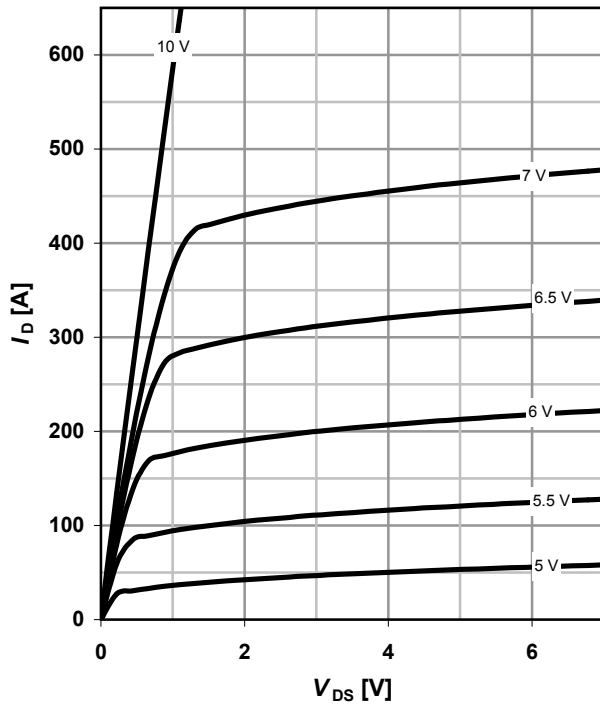
parameter:  $D = t_p/T$



**5 Typ. output characteristics**

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}$

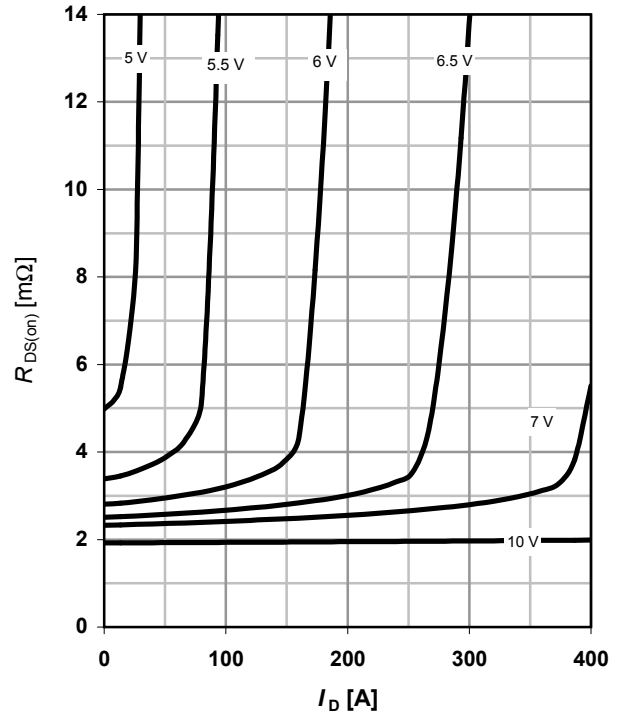
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}$

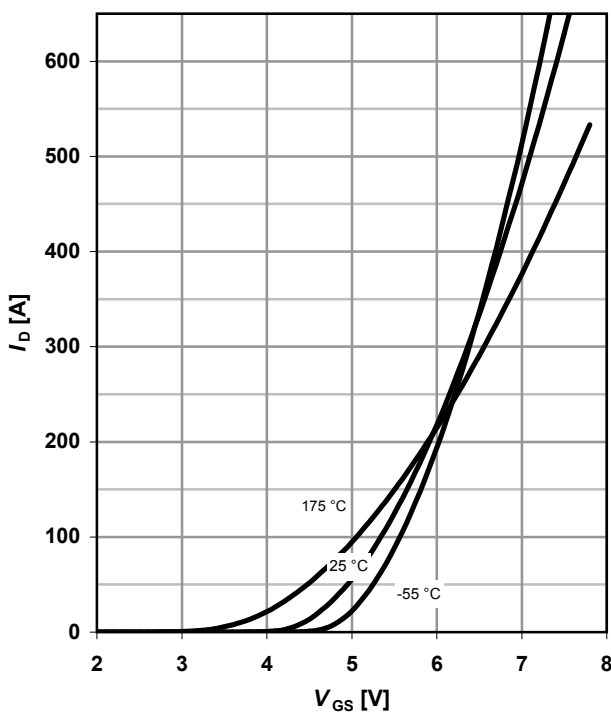
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

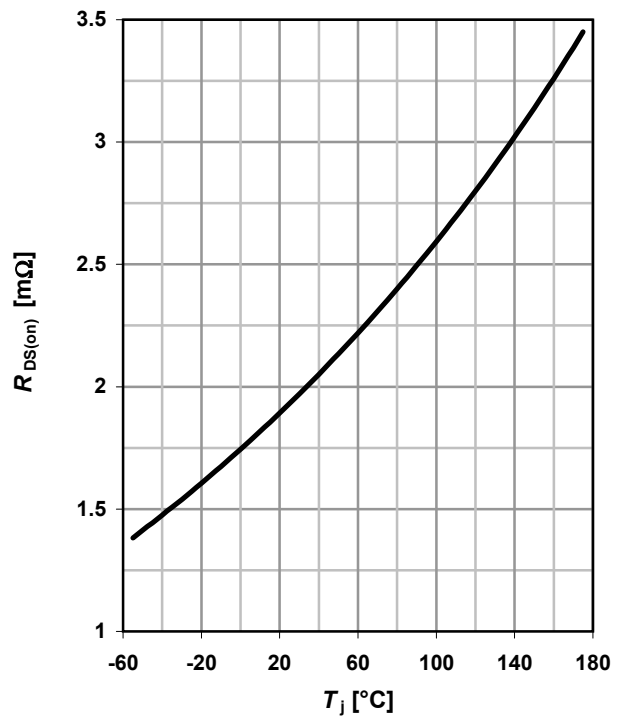
$I_D = f(V_{GS}); V_{DS} = 6\text{V}$

parameter:  $T_j$



**8 Typ. drain-source on-state resistance**

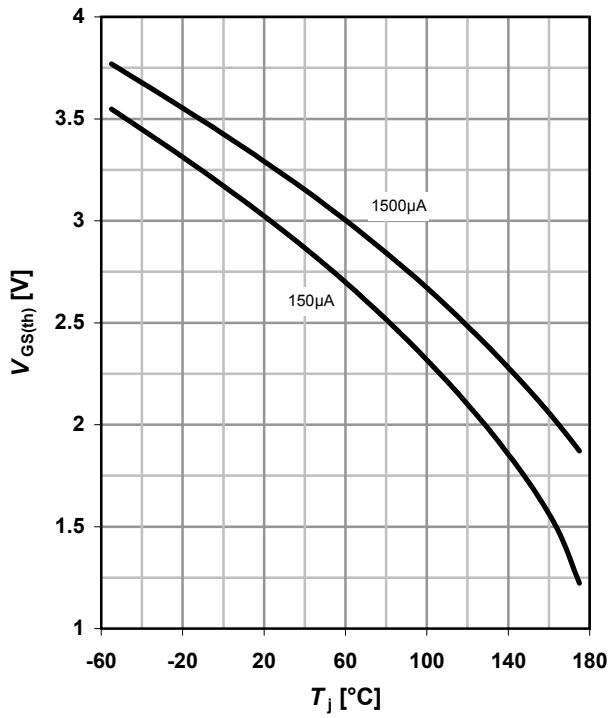
$R_{DS(on)} = f(T_j); I_D = 80\text{ A}; V_{GS} = 10\text{ V}$



**9 Typ. gate threshold voltage**

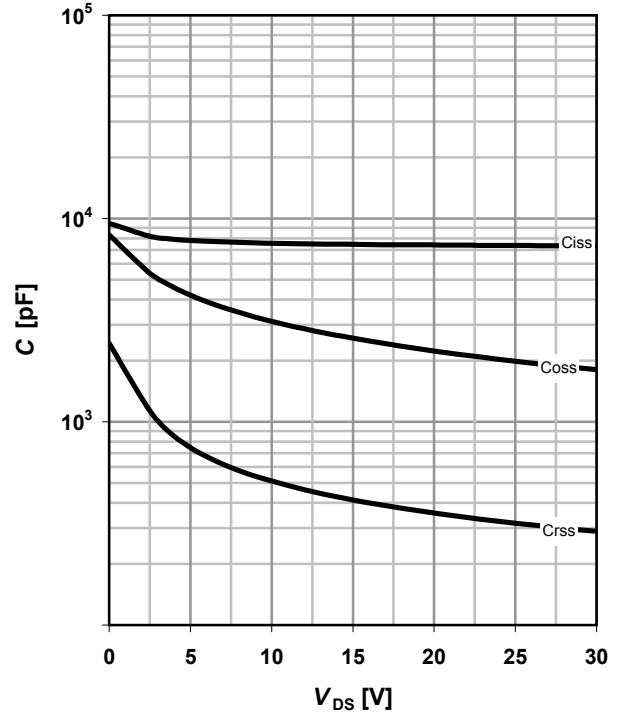
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter:  $I_D$



**10 Typ. capacitances**

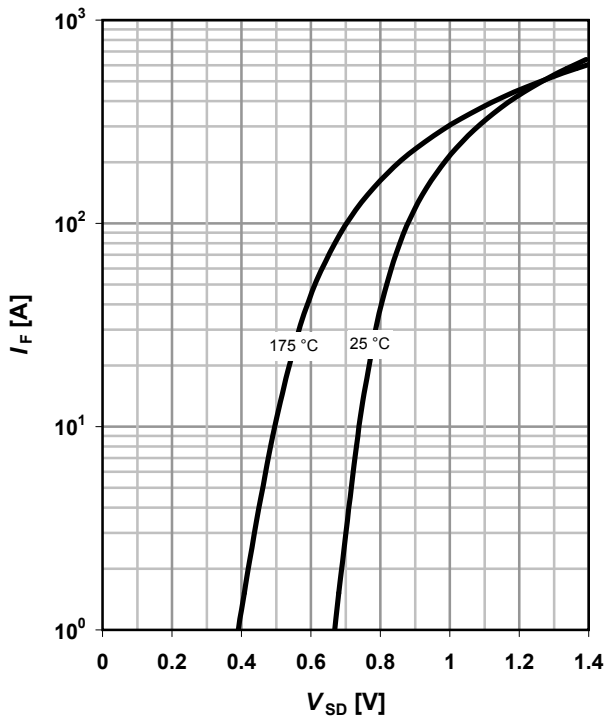
$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$



**11 Typical forward diode characteristics**

$I_F = f(V_{SD})$

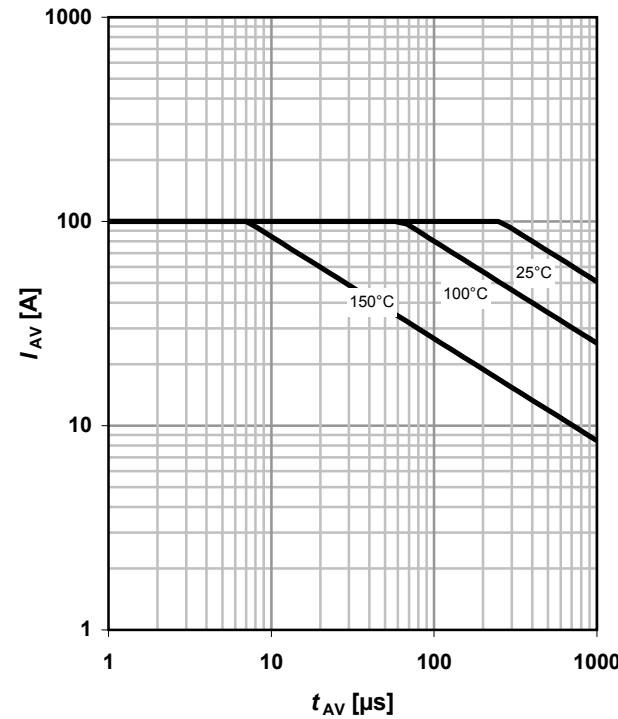
parameter:  $T_j$



**12 Typ. avalanche characteristics**

$I_{AS} = f(t_{AV})$

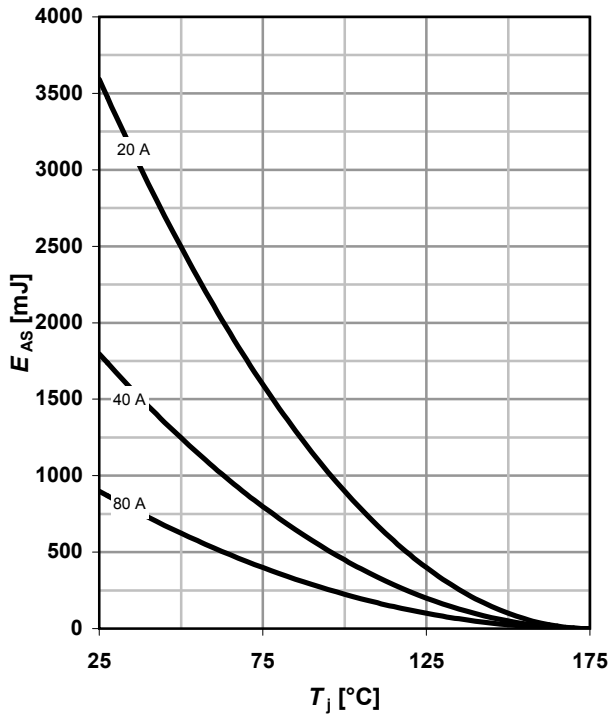
parameter:  $T_{j(start)}$



**13 Typical avalanche energy**

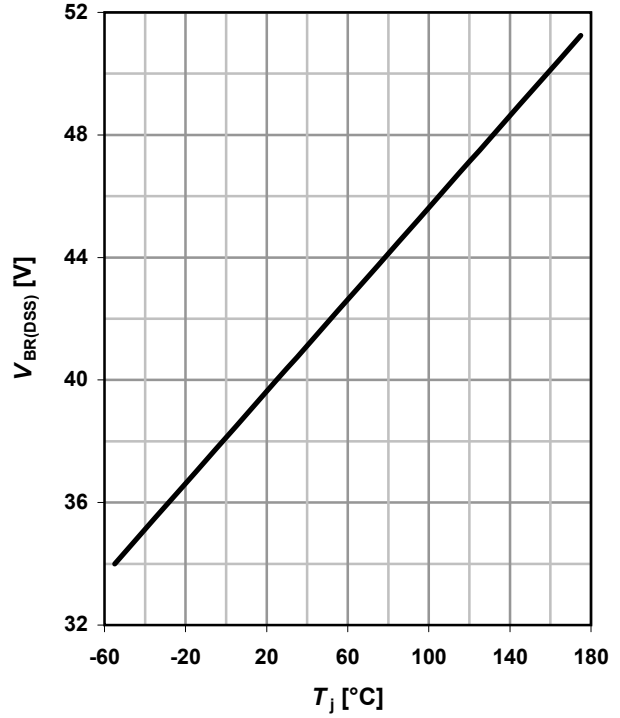
$$E_{AS} = f(T_j)$$

parameter:  $I_D$



**14 Drain-source breakdown voltage**

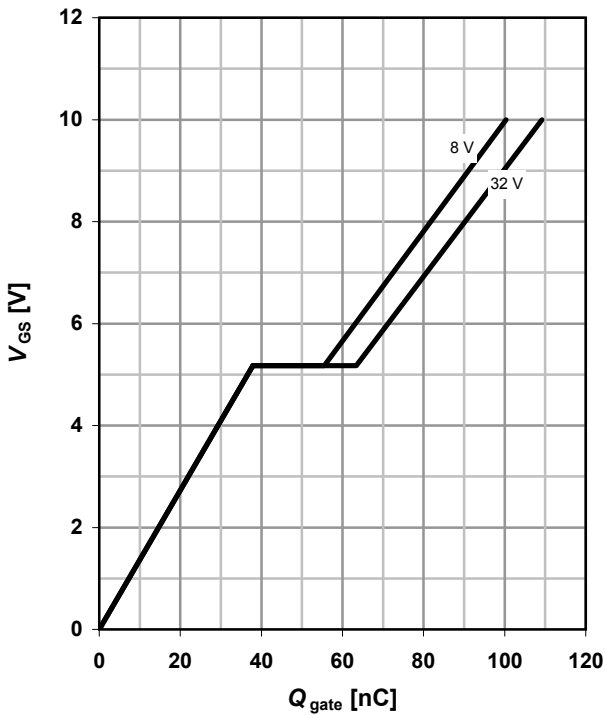
$$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$$



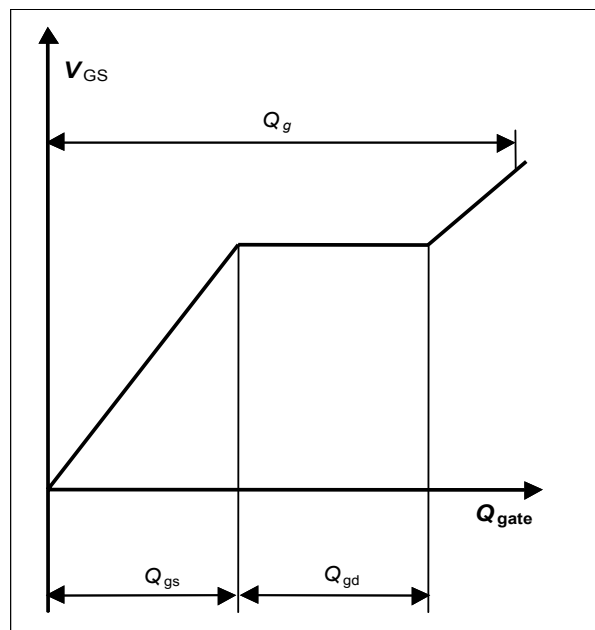
**15 Typ. gate charge**

$$V_{GS} = f(Q_{gate}); I_D = 80 \text{ A pulsed}$$

parameter:  $V_{DD}$



**16 Gate charge waveforms**



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